



Customer Information Notification

2023070071 : MC33XS2410 Data Sheet Update Rev 8.0 (Technical Clarifications / Corrections)

Note: This notice is NXP Company Proprietary.

Issue Date: Jul 27, 2023 **Effective date:** Jul 28, 2023

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Change Category

<input type="checkbox"/> Wafer Fab Process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Test Process	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab Materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Equipment	<input type="checkbox"/> Errata
<input type="checkbox"/> Wafer Fab Location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Location	<input type="checkbox"/> Electrical spec./Test coverage
<input type="checkbox"/> Firmware	<input checked="" type="checkbox"/> Other: Data Sheet Update (Technical Clarifications / Corrections)			

PCN Overview

Description

NXP Semiconductors announces the data sheet update to revision 8.0 for the MC33XS2410 four channel self-protected high-side switch devices associated with this notification.
Please see the revision history included in the updated document for a detailed description of the changes.

New MC33XS2410 revision 8.0 data sheet can be found attached to this notification and can be accessed at: <https://www.nxp.com/docs/en/data-sheet/MC33XS2410.pdf>

Corresponding ZVEI Delta Qualification Matrix ID: SEM-DS-02

Reason

The MC33XS2410 data sheet has been updated for technical clarifications and corrections associated with Rpd and Rpd_DI parameters as a result of the most recent characterization work.

Identification of Affected Products

Product identification does not change

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Data Sheet Revision

A new datasheet will be issued

Additional information

Additional documents: [view online](#)

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name	Eva Li
Position	Applications Engineering
e-mail address	jing-ampd.li@nxp.com

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NXP Quality Management Team.

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NXP Semiconductors
High Tech Campus, 5656 AG Eindhoven, The Netherlands

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Orderable Part Number#	12NC	Product Type	Product Description	Package Outline	Package Description	Product Status	Customer Specific Indicator	Product Line
MC33XS2410ELR2	934071255538	MC33XS2410ELR2	Q100	H(T)SSOP28	SOT1172-4	RFS	No	BLC3
MC33XS2410EL	934071255574	MC33XS2410EL	Q100	H(T)SSOP28	SOT1172-4	RFS	No	BLC3